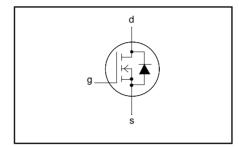
PowerMOS transistors Low capacitance Avalanche energy rated

PHP6NA60E

FEATURES

- Repetitive Avalanche Rated
- Fast switching
- · Low feedback capacitance
- Stable off-state characteristics
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$$V_{DSS} = 600 \text{ V}$$

$$I_D = 6.5 \text{ A}$$

$$R_{DS(ON)} \le 1.2 \Omega$$

GENERAL DESCRIPTION

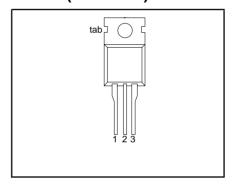
N-channel, enhancement mode field-effect power transistor, intended for use in off-line switched mode power supplies, T.V. and computer monitor power supplies, d.c. to d.c. converters, motor control circuits and general purpose switching applications.

The PHP6NA60E is supplied in the SOT78 (TO220AB) conventional leaded package.

PINNING

PIN	DESCRIPTION	
1	gate	
2	drain	
3	source	
tab	drain	

SOT78 (TO220AB)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DSS}	Drain-source voltage	T _i = 25 °C to 150°C	-	600	V
V_{DGR}	Drain-gate voltage	$T_i = 25 ^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$; $R_{GS} = 20 \text{k}\Omega$	-	600	V
V _{GS}	Gate-source voltage	, , , , , , , , , , , , , , , , , , , ,	-	± 30	V
l _D	Continuous drain current	$T_{mb} = 25 ^{\circ}\text{C}; V_{GS} = 10 \text{V}$ $T_{mb} = 100 ^{\circ}\text{C}; V_{GS} = 10 \text{V}$	-	6.5	Α
-		$T_{mb}^{ms} = 100 ^{\circ}\text{C}; V_{GS} = 10 \text{V}$	-	4.3	Α
I _{DM}	Pulsed drain current	$T_{mb}^{mb} = 25 ^{\circ}C$	-	26	Α
P̄̈́̈̀̄	Total dissipation	$T_{mb}^{\text{m}} = 25 ^{\circ}\text{C}$ $T_{mb} = 25 ^{\circ}\text{C}$	-	125	W
$\left[egin{array}{c} I_{DM} \ P_{D} \ T_{j}, T_{stg} \end{array} ight]$	Operating junction and	THE	- 55	150	°C
j. sig	storage temperature range				

AVALANCHE ENERGY LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
E _{AS}	Non-repetitive avalanche energy	Unclamped inductive load, $I_D = 6.5 \text{ A}$; $V_{DD} \le 50 \text{ V}$; starting $T_j = 25 ^{\circ}\text{C}$; $R_{GS} = 50 \Omega$; $V_{GS} = 10 \text{V}$	-	570	mJ
E _{AR} I _{AS} , I _{AR}	Repetitive avalanche energy ¹ Repetitive and non-repetitive avalanche current			9.5 6.5	mJ A

¹ pulse width and repetition rate limited by T_i max.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base		-	-	1	K/W
R _{th i-a}	Thermal resistance junction to ambient		-	60	-	K/W

ELECTRICAL CHARACTERISTICS

T_i = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.25 \text{ mA}$	600	-	-	V
$\Delta V_{(BR)DSS} / \Delta T_j$	Drain-source breakdown voltage temperature coefficient	$V_{DS} = V_{GS}; I_{D} = 0.25 \text{ mA}$	-	0.1	-	%/K
$\begin{matrix} R_{DS(ON)} \\ V_{GS(TO)} \\ g_{fs} \end{matrix}$	Drain-source on resistance Gate threshold voltage Forward transconductance	$V_{GS} = 10 \text{ V}; I_D = 3.25 \text{ A}$ $V_{DS} = V_{GS}; I_D = 0.25 \text{ mA}$ $V_{DS} = 30 \text{ V}; I_D = 3.25 \text{ A}$	2.0 3	3.0 4.5	1.2 4.0 -	Ω V S
I _{DSS}	Drain-source leakage current Gate-source leakage current	$V_{DS} = 600 \text{ V}; V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 ^{\circ}\text{C}$ $V_{GS} = \pm 30 \text{ V}; V_{DS} = 0 \text{ V}$	-	2 50 10	100 500 200	μΑ μΑ nA
$\begin{matrix} Q_{g(tot)} \\ Q_{gs} \\ Q_{gd} \end{matrix}$	Total gate charge Gate-source charge Gate-drain (Miller) charge	$I_D = 3 \text{ A}; V_{DD} = 480 \text{ V}; V_{GS} = 10 \text{ V}$		- 7 30	75 - -	n n n
$\begin{array}{c} t_{\text{d(on)}} \\ t_{\text{r}} \\ t_{\text{d(off)}} \\ t_{\text{f}} \end{array}$	Turn-on delay time Turn-on rise time Turn-off delay time Turn-off fall time	$V_{DD} = 300 \text{ V}; R_D = 47 \Omega;$ $R_G = 9.1 \Omega$		- - -	50 125 110 30	ns ns ns ns
L _d L _d L _s	Internal drain inductance Internal drain inductance Internal source inductance	Measured from tab to centre of die Measured from drain lead to centre of die Measured from source lead to source bond pad	1 1 1	3.5 4.5 7.5		nH nH nH
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	- 140 42	1550 - -	pF pF pF

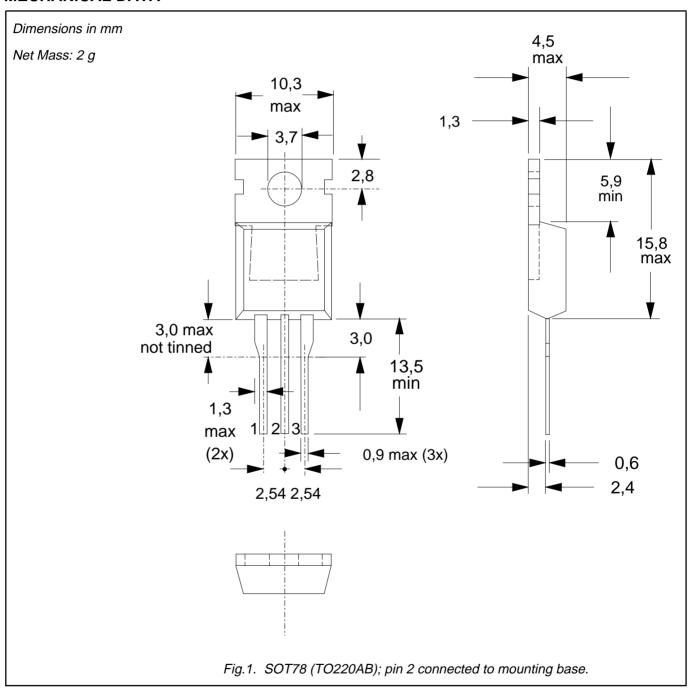
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _s	Continuous source current (body diode)	$T_{mb} = 25^{\circ}C$	-	-	6.5	Α
I _{SM}	Pulsed source current (body diode)	T _{mb} = 25°C	-	-	26	Α
V_{SD}	Diode forward voltage	$I_S = 6.5 \text{ A}; V_{GS} = 0 \text{ V}$	-	-	1.2	V
\mathbf{t}_{rr} \mathbf{Q}_{rr}	Reverse recovery time Reverse recovery charge	$I_S = 6.5 \text{ A}; V_{GS} = 0 \text{ V}; dI/dt = 100 \text{ A/}\mu\text{s}$	-	530 6.7	-	ns μC

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MECHANICAL DATA



- Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
 Refer to mounting instructions for SOT78 (TO220) envelopes.
 Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status				
Objective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification This data sheet contains preliminary data; supplementary data may be published later				
Product specification This data sheet contains final product specifications.				
Limiting values				

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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